



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



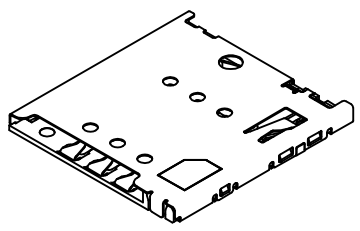
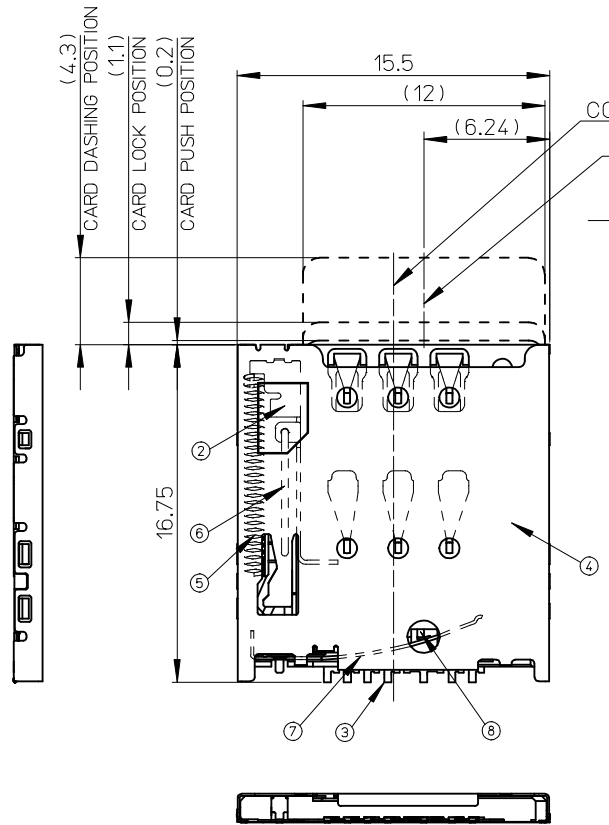
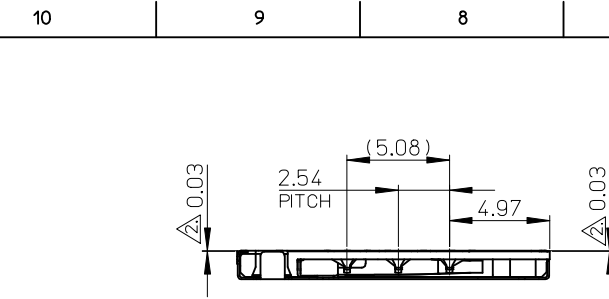
Contact us

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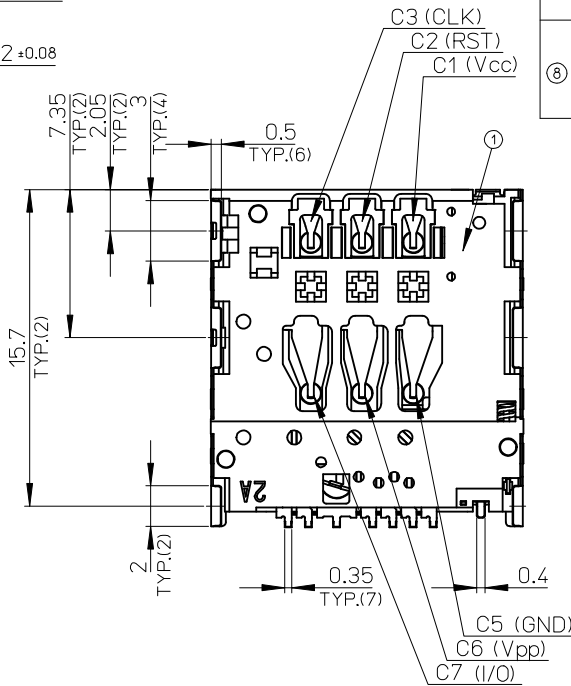
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PERSPECTIVE VIEW



番号 NO.	名称 NAME	材料 MATERIAL	仕上げ (めっき) FINISHES (PLATING)
①	ハウジング HOUSING	液晶ポリマー(LCP)、ガラス充填、UL94 V-0、黒 LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94 V-0, BLACK	
②	スライダー SLIDER	ステンレス鋼 STAINLESS STEEL	
③	ターミナル TERMINAL	焼青銅 PHOSPHOR BRONZE	接触部: 金めっき(0.5μmMIN.) 基板実装部: 金めっき 下地: ニッケルめっき(1.0μmMIN.) CONTACT AREA: GOLD PLATING (0.5 MICROMETER MINIMUM) SOLDER TAIL AREA: GOLD PLATING UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)
④	シェル SHELL	銅合金 COPPER ALLOY	
⑤	スプリング SPRING	ピアノ線 SWP	全面: ニッケルめっき NICKEL OVERALL
⑥	ピン PIN	ステンレス鋼 STAINLESS STEEL	
⑦	ディテクトレバー DETECT LEVER	焼青銅 PHOSPHOR BRONZE	接触部: 金めっき(0.2μmMIN.) 基板実装部: 金めっき 下地: ニッケルめっき(1.0μmMIN.) CONTACT AREA: GOLD PLATING (0.2 MICROMETER MINIMUM) SOLDER TAIL AREA: GOLD PLATING UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)
⑧	ディテクトスイッチ DETECT SWITCH	焼青銅 PHOSPHOR BRONZE	接触部: 金めっき(0.2μmMIN.) 基板実装部: 金めっき 下地: ニッケルめっき(1.0μmMIN.) CONTACT AREA: GOLD PLATING (0.2 MICROMETER MINIMUM) SOLDER TAIL AREA: GOLD PLATING UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)

NOTES

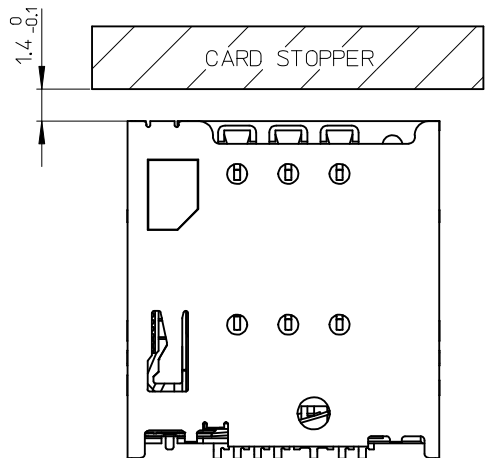
- ターミナル及びネイルの平坦度は 0.08 MAX. (測定用定板面を基準)
TERMINAL AND NAIL COPLANARITY TO BE 0.08 MAX.(FROM GAUGE PLANE)
 - スタンドオフ寸法
STAND OFF DIMENSION
本寸法はコネクタ全高に含まれます。
STAND OFF DIMENSION IS INCLUDED IN THE CONNECTOR TOTAL HEIGHT.
 - パターン禁止エリア PATTERN PROHIBITION AREA
 - カード検知スイッチ DETECT SWITCH
- | | |
|--------------------------------|------------|
| カード挿入時 CARD INSERTING POSITION | オープン OPEN |
| カード未挿入時 NO CARD | クローズ CLOSE |
- 肉抜き位置は任意とする。CAVITY IS TO BE OPTIONAL.
 - ロット印字は任意とする。LOT NUMBERING IS TO BE OPTIONAL.
 - ELV及びRoHS 適合品 ELV AND RoHS COMPLIANT.
 - 括弧寸法は、参考値となります。(Dimension) : REFERENCE VALUE

CONFIDENTIAL

503960-0695	6
EMBOSSED PACKAGE	極数
オーダー番号 ORDER NO.	CIRCUITS

CONNECTOR SERIES No. 503960-****

RELEASED EC NO: J2014-0885 DRWN: Y MORINAGA 2013/11/21 CHKD: TKUSUHARA01 2013/11/21 APPR: NUKITA 2013/11/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
		10 UNDER	±0.2	MM ONLY	1:1	METRIC	TITLE				
		10 OVER 30 UNDER	±0.25	DRAWN BY	DATE			MICRO SIM CARD CONN. PUSH/PUSH NORMAL TYPE ASS'Y			
		30 OVER	±0.3	CHECKED BY	DATE			molex			
		ANGULAR	±1 °	APPROVED BY	DATE						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
				SIZE	A3	SEE CHART		SD-503960-007			
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						1 OF 2	

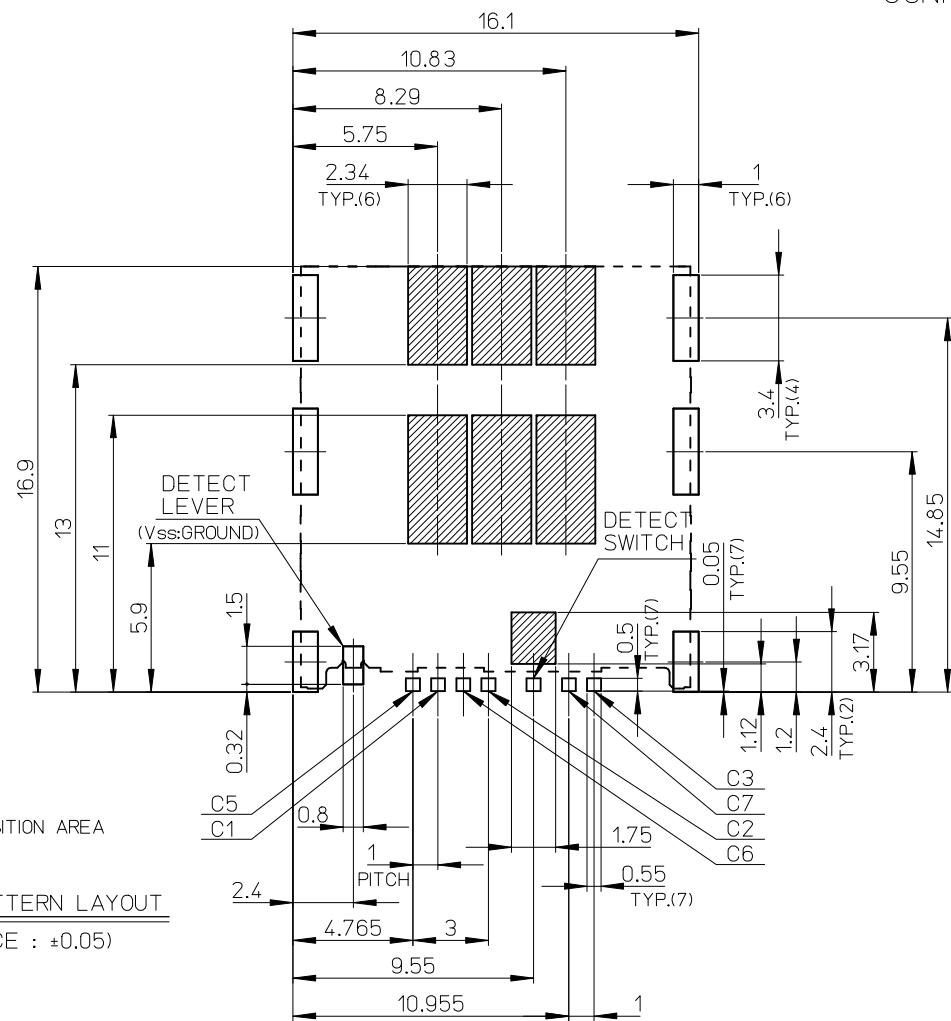


RECOMMENDED CARD STOPPER POSITION



パターン禁止エリア
PATTERN PROHIBITION AREA

RECOMMENDED PCB PATTERN LAYOUT
(GENERAL TOLERANCE : ±0.05)

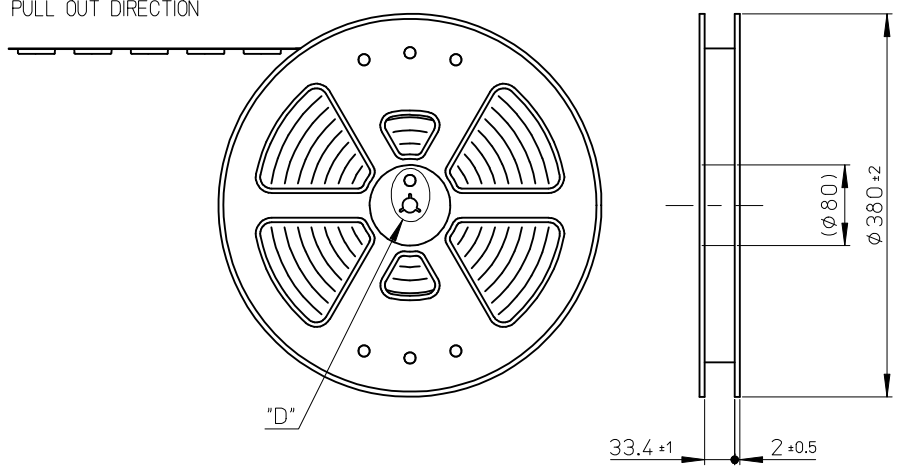


SEE SHEET 1 OF 2 EC NO: J2014-0885 DRWN: YMORINAGA 2013/11/21 CHKD: TKUSUHARA01 2013/11/21 APPR: NUKITA 2013/11/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YMORINAGA	DATE 2013/11/21	TITLE MICRO SIM CARD CONN. PUSH/PUSH NORMAL TYPE ASS'Y		
	10 OVER 30 UNDER	±0.25	CHECKED BY TKUSUHARA01	DATE 2013/11/21	molex DOCUMENT NO. SD-503960-007 SHEET NO. 2 OF 2		
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2013/11/21			
0	DESCRIPTION ANGULAR ±1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

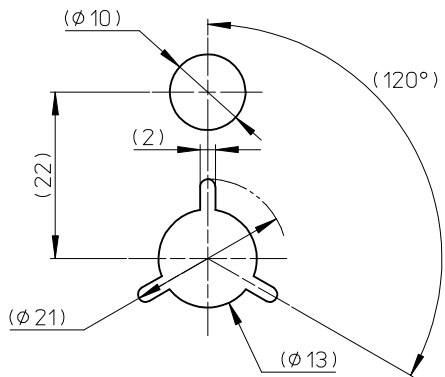
NOTES

- 製品詳細寸法については、コネクタ単体のSD図面を参照下さい。
RE DETAILED DIMENSION, SEE RSD DRAWING OF ASS'Y.
- 梱包数量：1600個/リール
NUMBER OF CONNECTORS：1600 PCS/REEL.
- リードテープ長さ LEAD TAPE LENGTH.

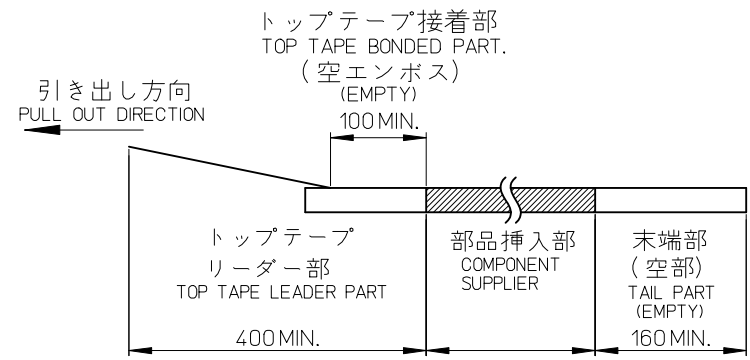
引き出し方向
PULL OUT DIRECTION



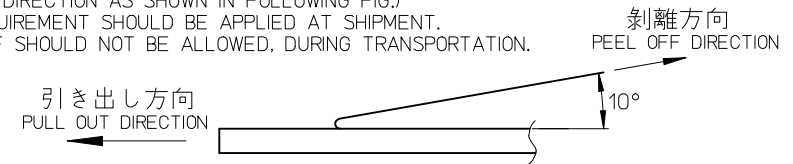
"D"



DETAIL "D"



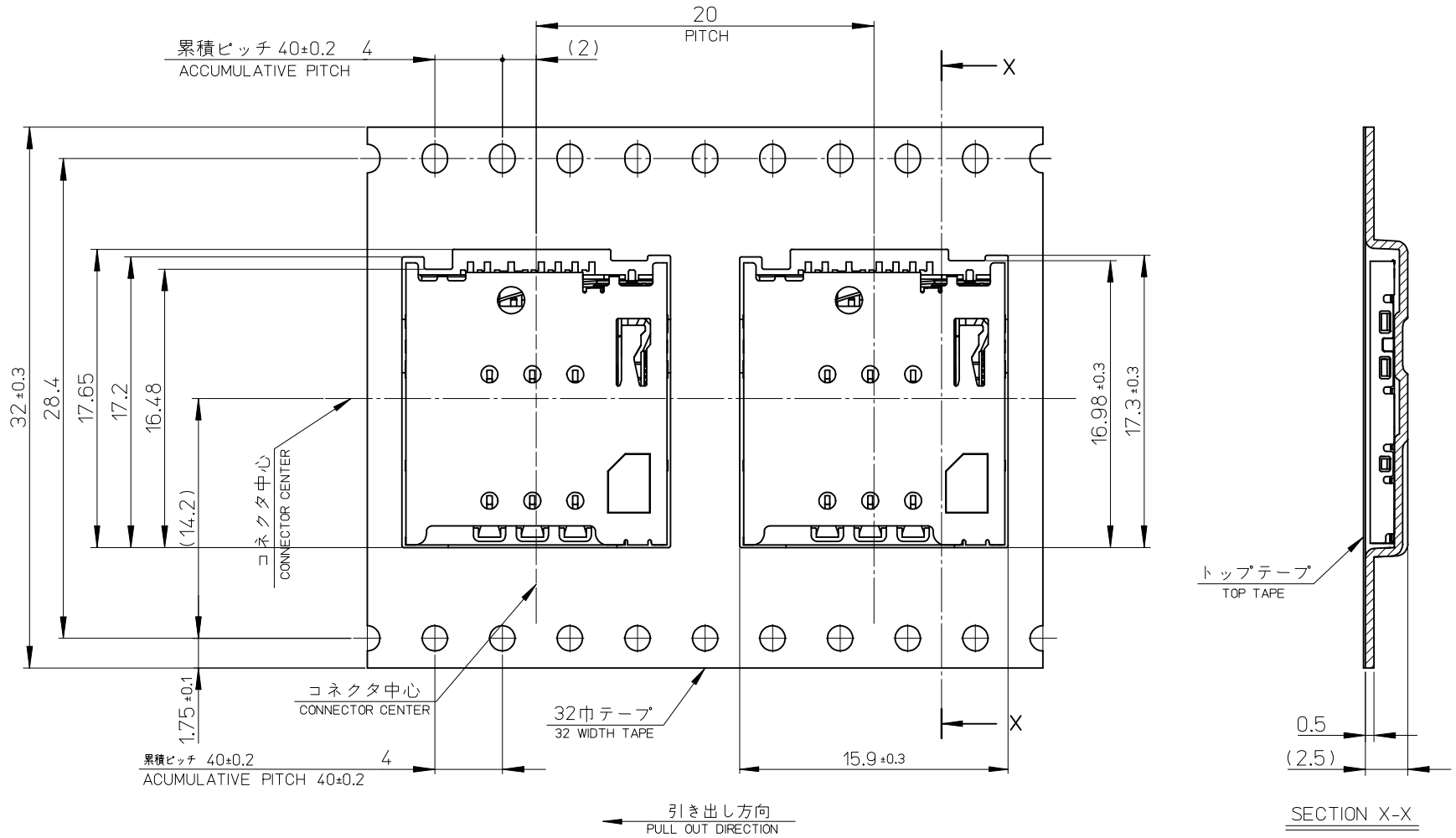
- トップテープの剥離強度：JIS C0806-3に準拠(剥離方向は下図参照)尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE：BASED UPON JIS C0806-3 (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.) THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE)：ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE)：PET, PE, PEF
リール (REEL)：ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

503960-0695	6
EMBOSSED PACKAGE	極数
オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 503960-****	

RELEASED EC NO: J2014-0885 DRWN: YMORINAGA 2013/11/20 CHKD: TKUSUHARA01 2013/11/20 APPR: NUKITA 2013/11/21 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YMORINAGA	DATE 2013/11/20	TITLE MICRO SIM CARD CONN. PUSH/PUSH NORMAL TYPE EMBOSSED TAPE PACKAGE		
	10 OVER 30 UNDER	±0.25	CHECKED BY TKUSUHARA01	DATE 2013/11/20			
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2013/11/21			
ANGULAR ±1 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-503960-008		SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



SEE SHEET 1 OF 2 EC NO: J2014-0885 DRWN: YMORINAGA 2013/11/20 CHKD: TKUSUHARA01 2013/11/20 APPR: NUKITA 2013/11/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY YMORINAGA	DATE 2013/11/20	TITLE MICRO SIM CARD CONN. PUSH/PUSH NORMAL TYPE EMBOSSED TAPE PACKAGE		
	10 OVER 30 UNDER	± 0.25	CHECKED BY TKUSUHARA01	DATE 2013/11/20	molex DOCUMENT NO. SD-503960-008 SHEET NO. 2 OF 2		
	30 OVER	± 0.3	APPROVED BY NUKITA	DATE 2013/11/21			
0	ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			